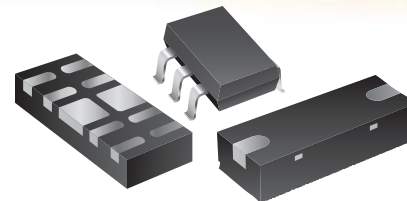


Product Change Notification

CHIP DIODES



August, 2013 - Revised April, 2014

Select Diodes

Changes to Die Manufacturing Location, Assembly Location and Materials

In order to meet the increasing demand for several diode products, Bourns proposes to implement the following changes:

1. Qualification of an alternate silicon manufacturing location
2. Qualification of an alternate assembly location
3. Qualification of Cu wire bonding (in addition to Au)

Not all these changes are applicable to every product; please refer to the table below:

Bourns Part Number	Alternate Silicon Manufacturing Location	Alternate Assembly Location	Cu Wire Bonding
CD143A-SR05LC		yes	yes
CD143A-SR2.8		yes	yes
CD143A-SR3.3		yes	yes
CDDFN10-0506N	yes		
CDDFN10-0524P	yes		
CDDFN2-T5.0LC	yes		
CDDFN6-0504P	yes		
CDMSP10-0504M	yes		yes
CDSC706-0504C	yes	yes	
CDSC706-T05CC		yes	
CDSOD323-T05M		yes	yes
CDSOT23-0502B		yes	yes
CDSOT23-0502U		yes	yes
CDSOT236-0502	yes		yes
CDSOT236-0504C	yes		yes
CDSOT236-0504LC	yes		yes
CDSOT563-0502	yes	yes	
CDNBS08-SLVU2.8-4		yes	yes

Impact on Form, Fit, Function and Reliability:

The above changes do not affect any of the electrical or mechanical parameters of the products. Form, fit, function and reliability are not impacted. Part markings and labeling are unchanged.

Identification of the Changed Products:

Traceability will be ensured through the lot code/date code.

Implementation Dates:

Samples: Available upon request

First date code using above changes: 1405

First production shipments: February 1, 2014

Summary of Qualification Results (Failing Parts/Tested Parts):

Test Item:	MSL	PCT w/pre-con	TCT w/pre-con	THT w/pre-con	HTST without/pre-con	Solderability
Description:	Moisture Sensitivity Level	Pressure Cooker Test	Temperature Cycle Test	Thermal/Humidity Test	High Temperature Storage Life	Solderability Test
Standard:	JESD22-A113 J-STD22-020D	JESD 22-A102-C	JESD22-A104B	JESD 22-A101-B	JESD22-A103B	JESD22-B102E
Test Conditions:	Baking: +125 °C, 24 hrs. Reflow Temp.: +260 °C -5/+0 °C, 3 times (1) MSL 3, Moisture Soak: +60 °C / 60 % RH, 40 hrs. (2) MSL 3, Moisture Soak: +30 °C / 60 % RH, 192 hrs. (3) MSL 1, Moisture Soak: +85 °C / 85 % RH, 168 hrs.	+121 °C, 100 % RH 2atm, 168 hrs.	-65 °C / +150 °C, 500 cycles	+85 °C, 85 % RH, 1000 hrs.	+150 °C, 1000 hrs.	Steam Aging: 93 °C (-5/+3 °C) / 8 hrs. Flux: +245 °C / 5 sec.
CDSOT236-0502	MSL3 - 0/66 (2)	0/22	0/22	0/22	0/22	N/A
CD143A-SR05LC	MSL3 - 0/66 (1)	0/22	0/22	0/22	0/22	0/5
CDDFN10-0524P	MSL3 - 0/231 (1)	0/77	0/77	0/77	0/77	N/A
CDMSP10-0504M	MSL3 - 0/66 (1)	0/22	0/22	0/22	0/22	N/A
CDSOT236-0504LC	MSL3 - 0/66 (1)	0/22	0/22	0/22	0/22	N/A
CDDFN10-0506N	MSL3 - 0/66 (1)	0/22	0/22	0/22	0/22	N/A
CDSOT23-0502U	MSL3 - 0/66 (1)	0/22	0/22	0/22	0/22	0/5
CDSOT23-0502B	MSL3 - 0/66 (1)	0/22	0/22	0/22	0/22	0/5
CDCS706-T05CC	MSL3 - 0/66 (2)	0/22	0/22	0/22	0/22	0/5
CDSOD323-T05M	MSL3 - 0/66 (1)	0/22	0/22	0/22	0/22	0/5
CDDFN2-T5.0LC	MSL3 - 0/231 (3)	0/77	0/77	0/77	0/77	0/5
CDCS706-0504C	MSL3 - 0/66 (1)	0/22	0/22	0/22	0/22	0/5
CDSOT236-0504C	MSL3 - 0/66 (1)	0/22	0/22	0/22	0/22	N/A
CDSOT563-0502	MSL3 - 0/66 (1)	0/22	0/22	0/22	0/22	0/5
CDNBS08-SLVU2.8-4	MSL3 - 0/66 (2)	0/22	0/22	0/22	0/22	0/5

If you have any questions or need additional information, please feel free to contact [Customer Service/Inside Sales](#).